Dual 5 A High Speed Low-Side MOSFET Drivers with Enable

NCP81071

NCP81071 is a high speed dual low−side MOSFETs driver. It is capable of providing large peak currents into capacitive loads. This driver can deliver 5 A peak current at the Miller plateau region to help reduce the Miller effect during MOSFETs switching transition. This driver also provides enable functions to give users better control capability in different applications. ENA and ENB are implemented on pin 1 and pin 8 which were previously unused in the industry standard pin−out. They are internally pulled up to driver's input voltage for active high logic and can be left open for standard operations. This part is available in MSOP8−EP package, SOIC8 package and WDFN8 3 mm x 3 mm package.

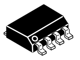
Features

- High Current Drive Capability ±5 A
- TTL/CMOS Compatible Inputs Independent of Supply Voltage
- Industry Standard Pin−out
- High Reverse Current Capability (6 A) Peak
- Enable Functions for Each Driver
- 8 ns Typical Rise and 8 ns Typical Fall Times with 1.8 nF Load
- Typical Propagation Delay Times of 20 ns with Input Falling and 20 ns with Input Rising
- Input Voltage from 4.5 V to 20 V
- Dual Outputs can be Paralleled for Higher Drive Current
- These Devices are Pb−Free, Halogen Free/BFR Free and are RoHS Compliant

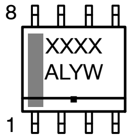
Applications

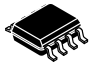
- Server Power
- Telecommunication, Datacenter Power
- Synchronous Rectifier
- Switch Mode Power Supply
- DC/DC Converter
- Power Factor Correction
- Motor Drive
- Renewable Energy, Solar Inverter

MARKING DIAGRAMS

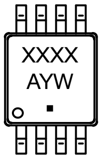


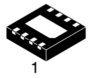
SOIC−8
D SUFFIX
CASE 751



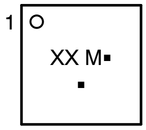


MSOP−8
Z SUFFIX
CASE 846AM





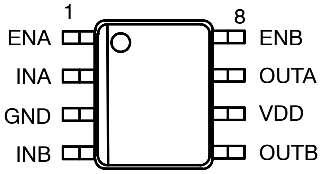
WDFN8
MN SUFFIX
CASE 511CD



XX = Specific Device Code
A = Assembly Location
L = Wafer Lot
Y = Year
W = Work Week
M = Date Code
▪ = Pb−Free Package

(Note: Microdot may be in either location)

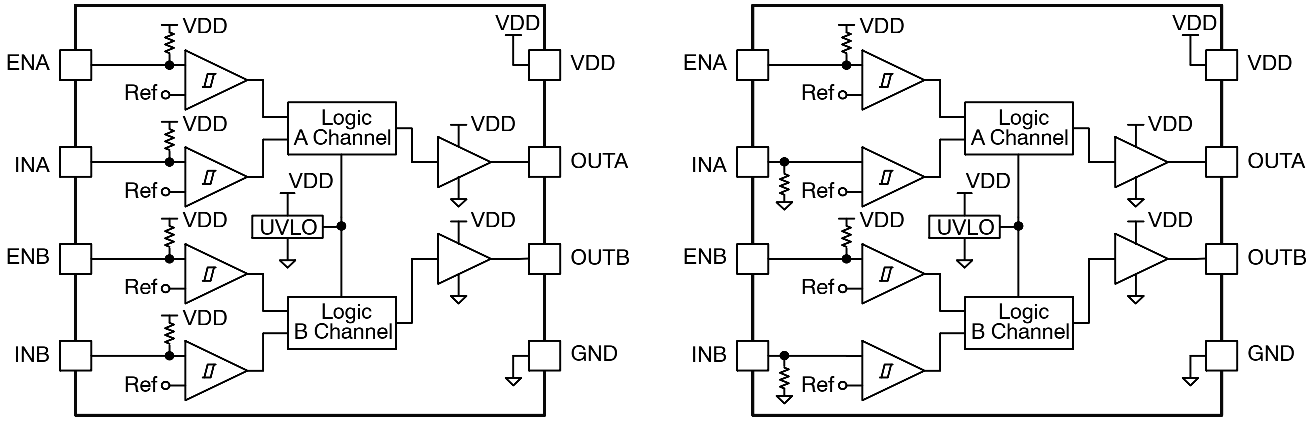
PIN CONNECTIONS



(Top View)

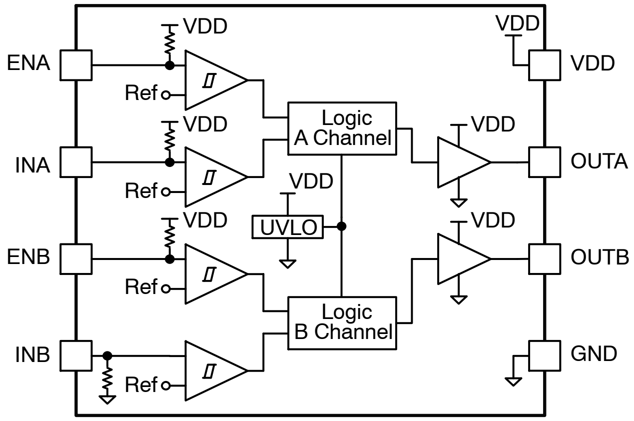
ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 11 of this data sheet.



NCP81071A

NCP81071B



NCP81071C

Figure 1. NCP81071 Block Diagram

Table 1. PIN DESCRIPTION

Pin No.	Symbol	Description
1	ENA	Enable input for the driver channel A with logic compatible threshold and hysteresis. This pin is used to enable and disable the driver output. It is internally pulled up to VDD with a 200 kΩ resistor for active high operation. The output of the pin when the device is disabled will be always low.
2	INA	Input of driver channel A which has logic compatible threshold and hysteresis. If not used, this pin should be connected to either VDD or GND. It should not be left unconnected.
3	GND	Common ground. This ground should be connected very closely to the source of the power MOSFET.
4	INB	Input of driver channel B which has logic compatible threshold and hysteresis. If not used, this pin should be connected to either VDD or GND. It should not be left unconnected.
5	OUTB	Output of driver channel B. The driver is able to provide 5 A drive current to the gate of the power MOSFET.
6	VDD	Supply voltage. Use this pin to connect the input power for the driver device.
7	OUTA	Output of driver channel A. The driver is able to provide 5 A drive current to the gate of the power MOSFET.
8	ENB	Enable input for the driver channel B with logic compatible threshold and hysteresis. This pin is used to enable and disable the driver output. It is internally pulled up to VDD with a 200 kΩ resistor for active high operation. The output of the pin when the device is disabled will be always low.

TYPICAL APPLICATION CIRCUIT

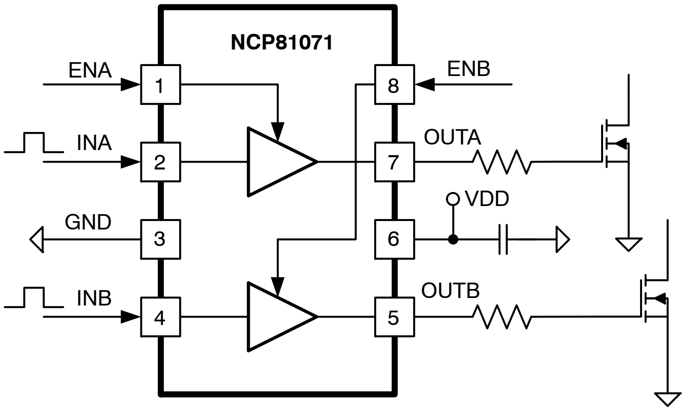


Table 2. ABSOLUTE MAXIMUM RATINGS

		Value		Unit
		Min	Max	
Supply Voltage	VDD	−0.3	24	V
Output Current (DC)	Iout_dc	0.3		A
Reverse Current (Pulse< 1 μs)			6.0	A
Output Current (Pulse < 0.5 μs)	Iout_pulse	6.0		A
Input Voltage	INA, INB	−6.0	VDD+0.3	V
Enable Voltage	ENA, ENB	−0.3	VDD+0.3	
Output Voltage	OUTA, OUTB	−0.3	VDD+0.3	V
Output Voltage (Pulse < 0.5 μs)	OUTA, OUTB	−3.0	VDD+3.0	V
Junction Operation Temperature	T_J	−40	150	°C
Storage Temperature	T_{stg}	−65	160	
Electrostatic Discharge	Human body model, HBM	4000		V
	Charge device model, CDM	1000		
OUTA OUTB Latch−up Protection		500		mA

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

Table 3. RECOMMENDED OPERATING CONDITIONS

Parameter	Rating	Unit
VDD supply Voltage	4.5 to 20	V
INA, INB input voltage	−5.0 to VDD	V
ENA, ENB input voltage	0 to VDD	V
Junction Temperature Range	−40 to +140	°C

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

Table 4. THERMAL INFORMATION

Package	θ_{JA} (°C/W)	θ_{JC} (°C/W)	Ψ_{JT} (°C/W) (Note 1)
SOIC−8	115	50	
MSOP−8 EP	39	4.7	11
WDFN8 3x3	39	4.7	

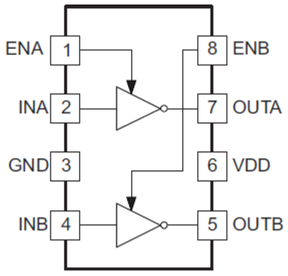
1. Ψ_{JT}: approximate thermal impedance, junction−to−case top.

Table 5. INPUT/OUTPUT TABLE

ENA	ENB	INA	INB	NCP81071A		NCP81071B		NCP81071C	
				OUTA	OUTB	OUTA	OUTB	OUTA	OUTB
H	H	L	L	H	H	L	L	H	L
H	H	L	H	H	L	L	H	H	H
H	H	H	L	L	H	H	L	L	L
H	H	H	H	L	L	H	H	L	H
L	L	Any	Any	L	L	L	L	L	L
Any	Any	x (Note 2)	x (Note 2)	L	L	L	L	L	L
x (Note 2)	x (Note 2)	L	L	H	H	L	L	H	L
x (Note 2)	x (Note 2)	L	H	H	L	L	H	H	H
x (Note 2)	x (Note 2)	H	L	L	H	H	L	L	L
x (Note 2)	x (Note 2)	H	H	L	L	H	H	L	H

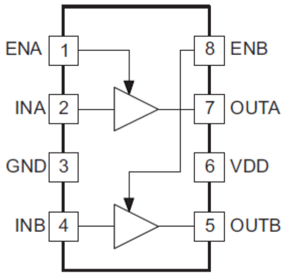
2. Floating condition, internal resistive pull up or pull down configures output condition

PRODUCT MATRIX



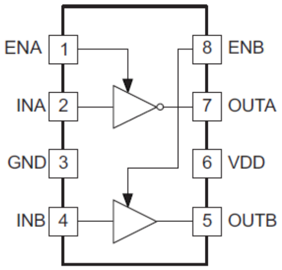
(DUAL INVERTING)

NCP81071A



(DUAL NON-INVERTING)

NCP81071B



(ONE INVERTING,
ONE NON-INVERTING)

NCP81071C

Table 6. ELECTRICAL CHARACTERISTICS
(Typical values: V_{DD} =12 V, 1 µF from V_{DD} to GND, $T_A = T_J = -40°C$ to 140°C, typical at T_{AMB} = 25°C, unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Units
SUPPLY VOLTAGE						
VDD Under Voltage Lockout (rising)	V_{CCR}	VDD rising	3.5	4.0	4.5	V
VDD Under Voltage Lockout (hysteresis)	V_{CCH}			400		mV
Operating Current (no switching)	I_{DD}	INA = 0, INB = 5 V, ENA = ENB = 0 INA = 5 V, INB = 0, ENA = ENB = 0 INA = 0, INB = 5 V, ENA = ENB = 5 V INA = 5 V, INB = 0, ENA = ENB = 5 V		1.4	3	mA
VDD Under Voltage Lockout to Output Delay (Note 3)		VDD rising		10		µs
INPUTS						
High Threshold	V_{thH}	Input rising from logic low	1.8	2.0	2.2	V
Low Threshold	V_{thL}	Input falling from logic high	0.8	1.0	1.2	V
INA, INB Pull−Up Resistance		OUTA = OUTB = Inverter Configuration		200		kΩ
INA, INB Pull−Down Resistance		OUTA = OUTB = Buffer Configuration		200		kΩ
OUTPUTS						
Output Resistance High	R_{OH}	IOUT = −10 mA		0.8	2	Ω
Output Resistance Low	R_{OL}	IOUT = +10 mA		0.8	2	Ω
Peak Source Current (Note 4)	I_{Source}	OUTA/OUTB = GND 200 ns Pulse		5		A
Miller Plateau Source Current (Note 4)	I_{Source}	OUTA/OUTB = 5.0 V 200 ns Pulse		4.5		A
Peak Sink Current (Note 4)	I_{Sink}	OUTA/OUTB = VDD 200 ns Pulse		5		A
Miller Plateau Sink Current (Note 4)	I_{Sink}	OUTA/OUTB = 5.0 V 200 ns Pulse		3.5		A
ENABLE						
High−Level Input Voltage	V_{IN_H}	Low to High Transition	1.8	2.0	2.2	V
Low−Level Input Voltage	V_{IN_L}	High to Low Transition	0.8	1.0	1.2	V
ENA, ENB pull−up resistance				200		kΩ
Propagation Delay Time (EN to OUT) (Notes 3, 5)	t_{d3}	C_{Load} = 1.8 nF	16	20	29	ns
Propagation Delay Time (EN to OUT) (Notes 3, 5)	t_{d4}	C_{Load} = 1.8 nF	16	20	29	ns
SWITCHING CHARACTERISTICS						
Propagation Delay Time Low to High, IN Rising (IN to OUT) (Notes 3, 5)	t_{d1}	C_{Load} = 1.8 nF	16	20	29	ns
Propagation Delay Time High to Low, IN Falling (IN to OUT) (Notes 3, 5)	t_{d2}	C_{Load} = 1.8 nF	16	20	29	ns
Rise Time (Note 5)	t_r	C_{Load} = 1.8 nF		8	15	ns
Fall Time (Note 5)	t_f	C_{Load} = 1.8 nF		8	15	ns
Delay Matching between 2 Channels (Note 6)	t_m	INA = INB, OUTA and OUTB at 50% Transition Point		1	4	ns

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

3. Guaranteed by design.
4. Not production tested, guaranteed by design and statistical analysis.
5. See timing diagrams in Figure 2, Figure 3, Figure 4 and Figure 5.
6. Guaranteed by characterization.

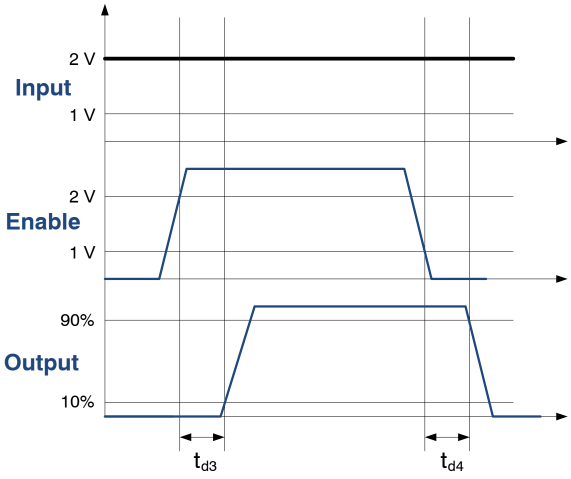


Figure 2. Enable Function for Non−inverting Input Driver Operation

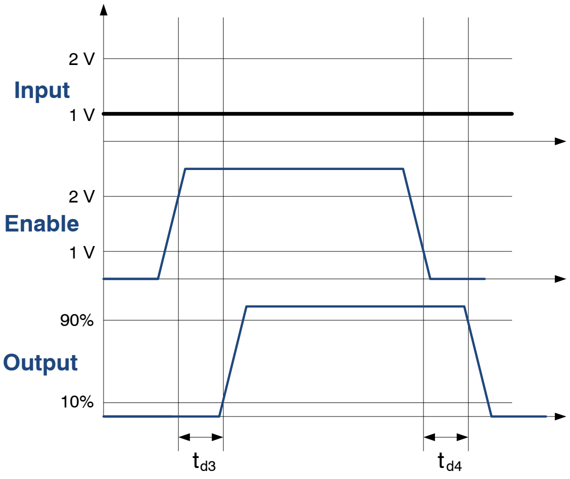


Figure 3. Enable Function for Inverting Input Driver Operation

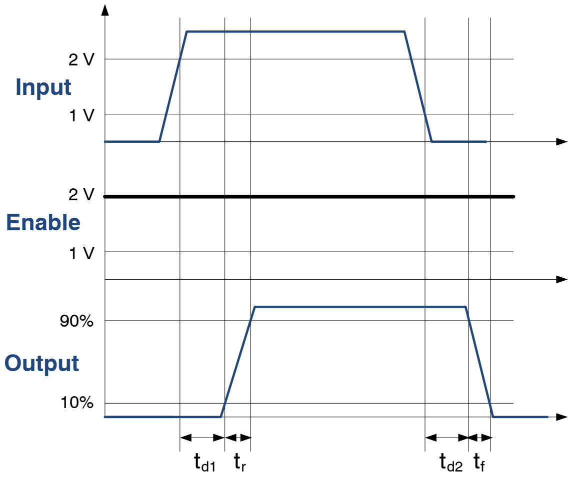


Figure 4. Non−inverting Input Driver Operation

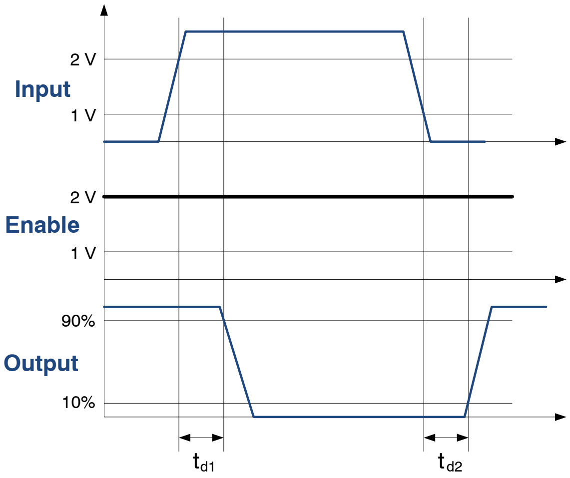


Figure 5. Inverting Input Driver Operation

TYPICAL CHARACTERISTICS

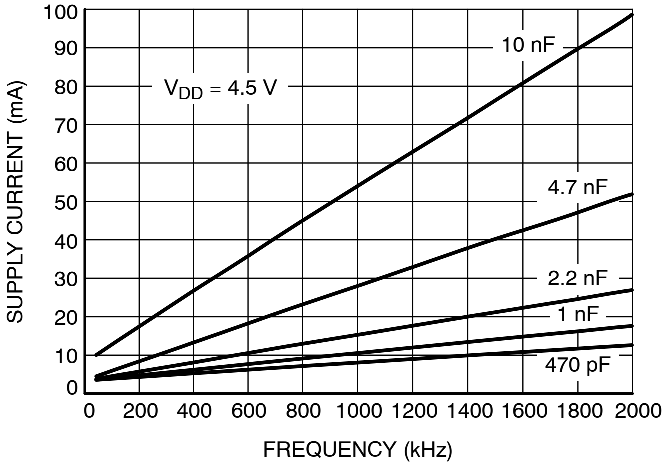


Figure 6. Supply Current vs. Switching Frequency (V_{DD} = 4.5 V)

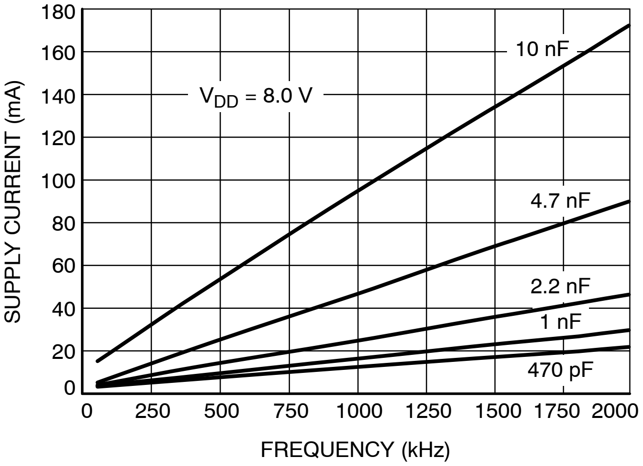


Figure 7. Supply Current vs. Switching Frequency (V_{DD} = 8 V)

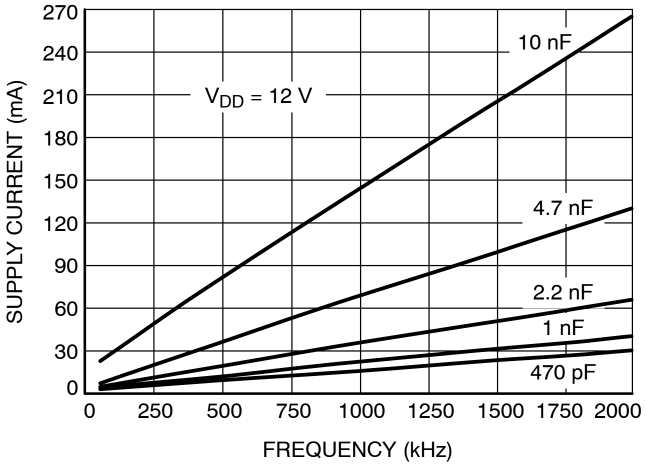


Figure 8. Supply Current vs. Switching Frequency (V_{DD} = 12 V)

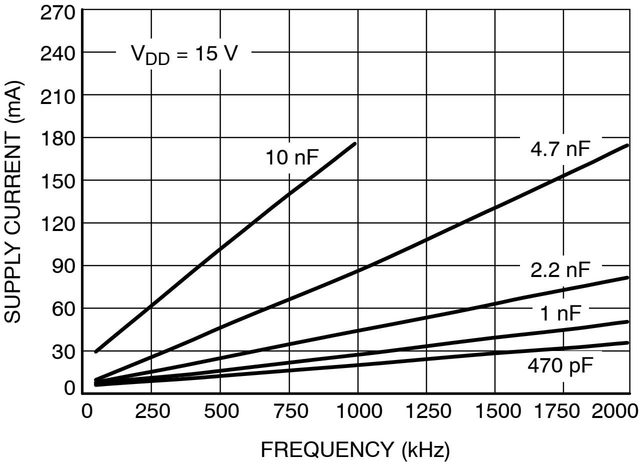


Figure 9. Supply Current vs. Switching Frequency (V_{DD} = 15 V)

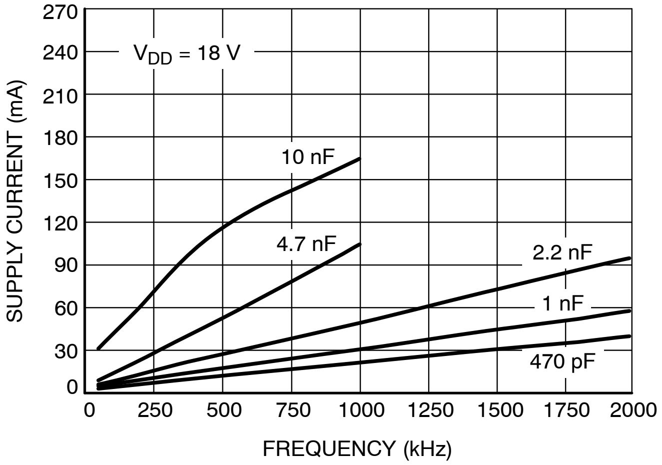


Figure 10. Supply Current vs. Switching Frequency (V_{DD} = 18 V)

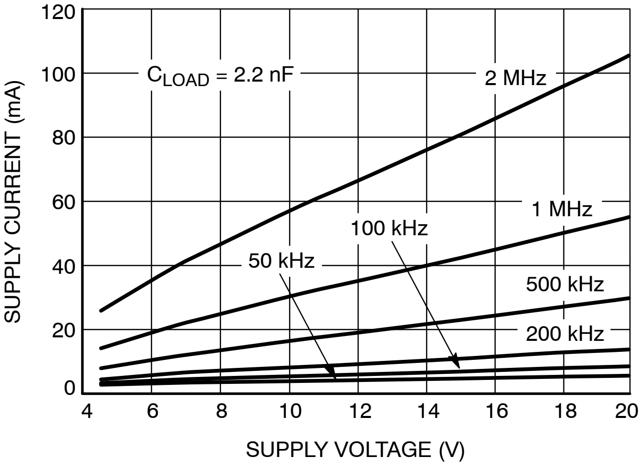


Figure 11. Supply Current vs. Supply Voltage (C_{LOAD} = 2.2 nF)

TYPICAL CHARACTERISTICS

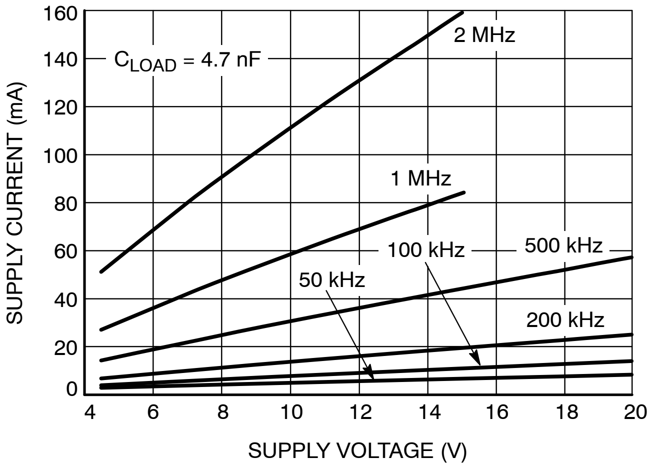


Figure 12. Supply Current vs. Supply Voltage (C_{LOAD} = 4.7 nF)

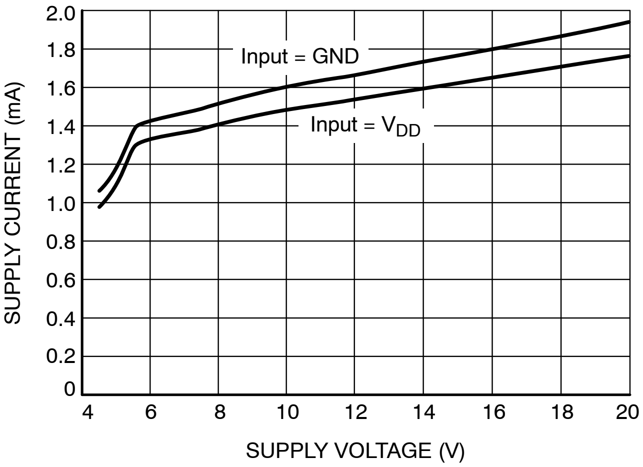


Figure 13. Supply Current vs. Supply Voltage (NCP81071A)

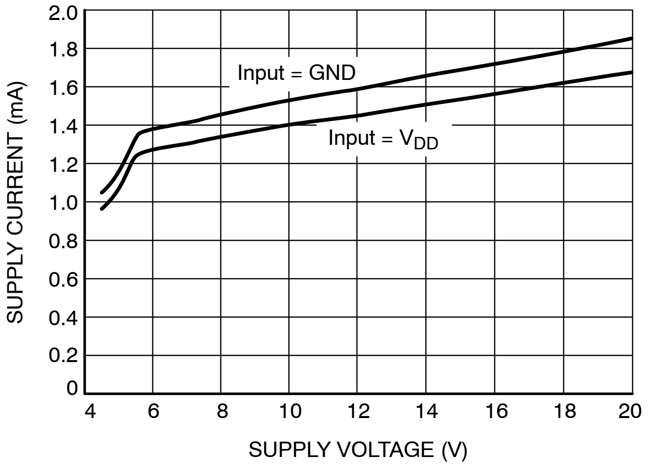


Figure 14. Supply Current vs. Supply Voltage (NCP81071B)

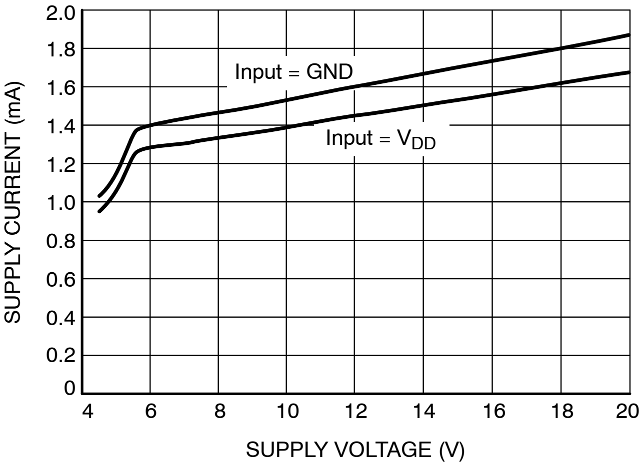


Figure 15. Supply Current vs. Supply Voltage (NCP81071C)

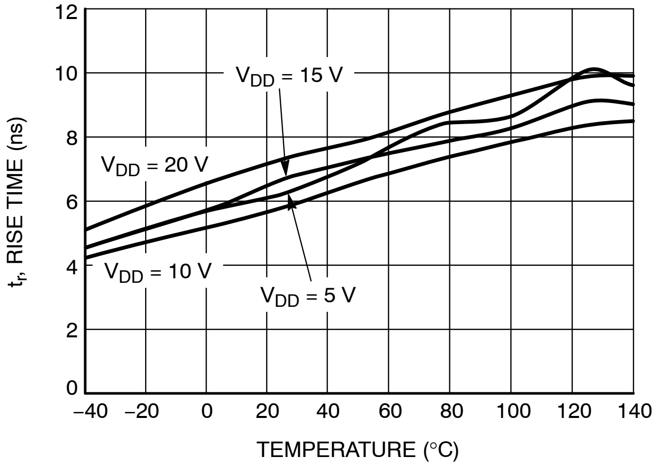


Figure 16. Rise Time vs. Temperature

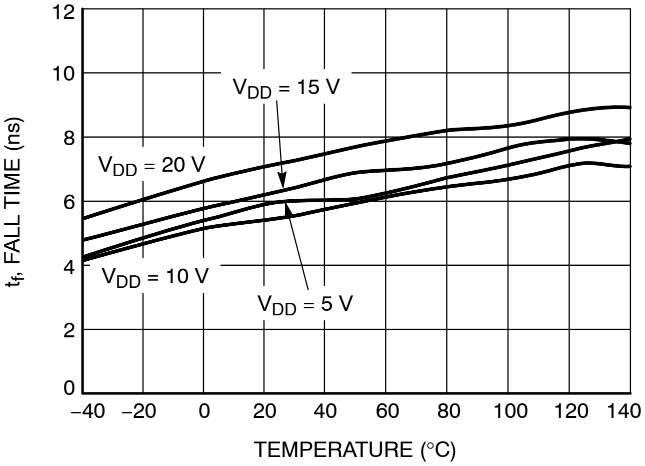


Figure 17. Fall Time vs. Temperature

TYPICAL CHARACTERISTICS

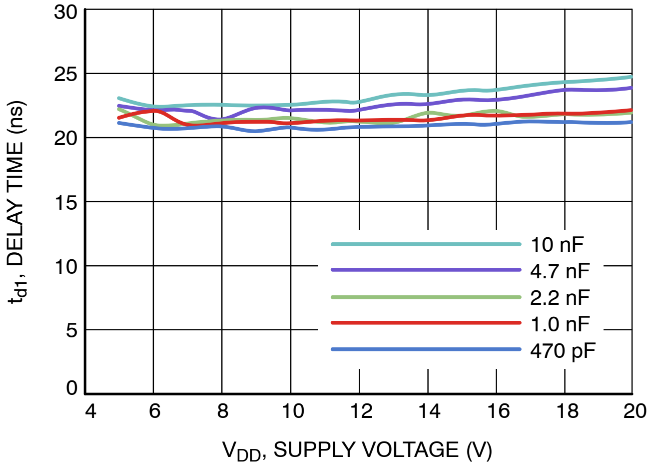


Figure 18. Propagation Delay t_{d1} vs. Supply Voltage

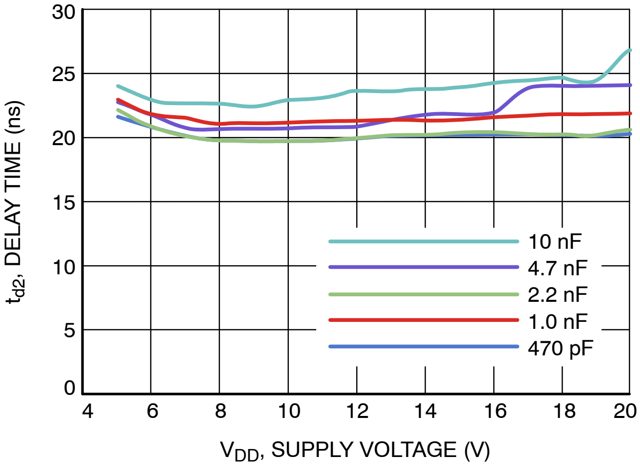


Figure 19. Propagation Delay t_{d2} vs. Supply Voltage

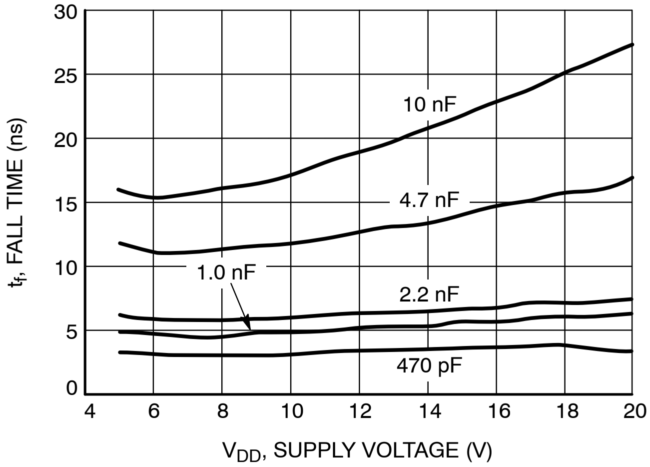


Figure 20. Fall Time t_f vs. Supply Voltage

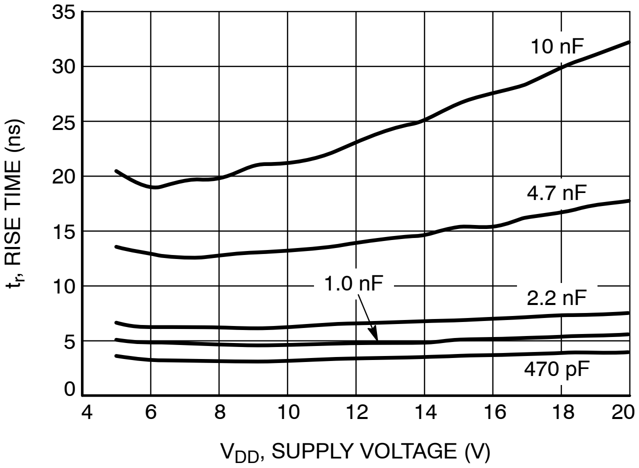


Figure 21. Rise Time t_r vs. Supply Voltage

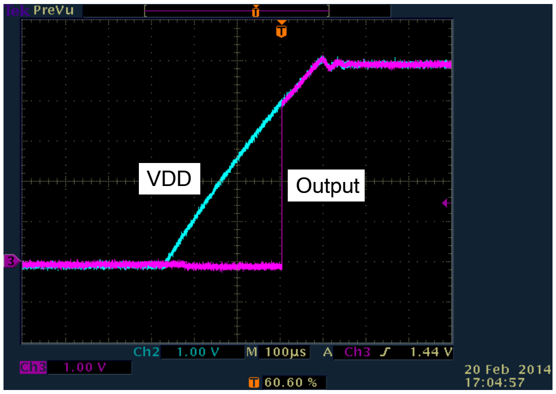


Figure 22. Output Behavior vs. Supply Voltage NCP81071A (Inverting) 10 nF between Output and GND, INA = GND, ENA = VDD

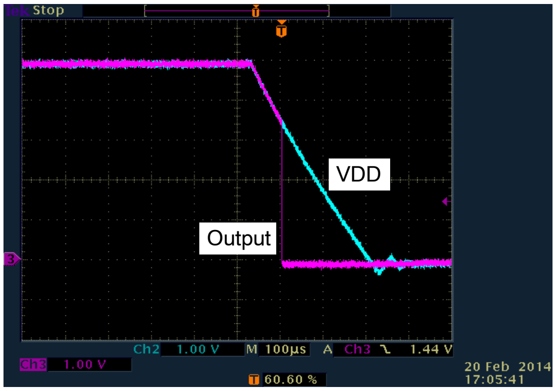


Figure 23. Output Behavior vs. Supply Voltage NCP81071A (Inverting) 10 nF between Output and GND, INA = GND, ENA = VDD

TYPICAL CHARACTERISTICS

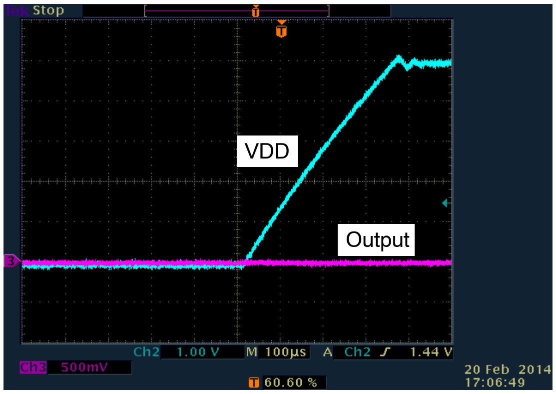


Figure 24. Output Behavior vs. Supply Voltage NCP81071A (Inverting) 10 nF between Output and GND, INA = VDD, ENA = VDD

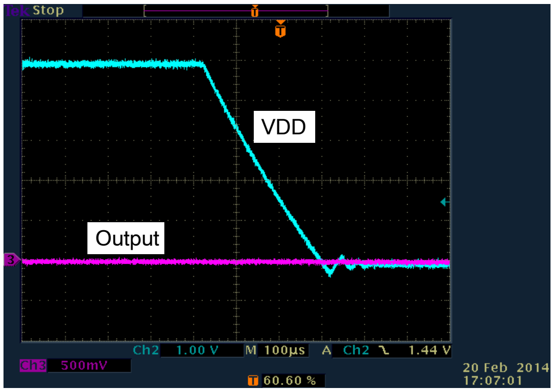


Figure 25. Output Behavior vs. Supply Voltage NCP81071A (Inverting) 10 nF between Output and GND, INA = VDD, ENA = VDD

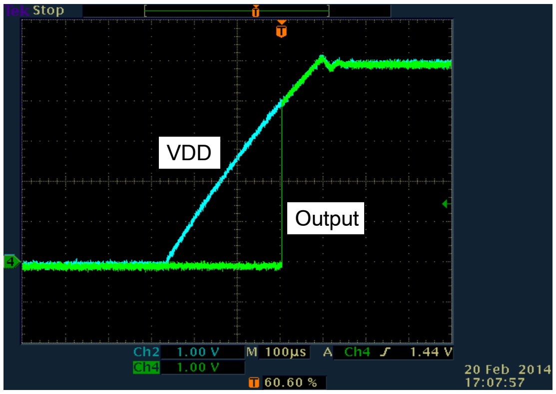


Figure 26. Output Behavior vs. Supply Voltage NCP81071B (Non−Inverting) 10 nF between Output and GND, INA = VDD, ENA = VDD

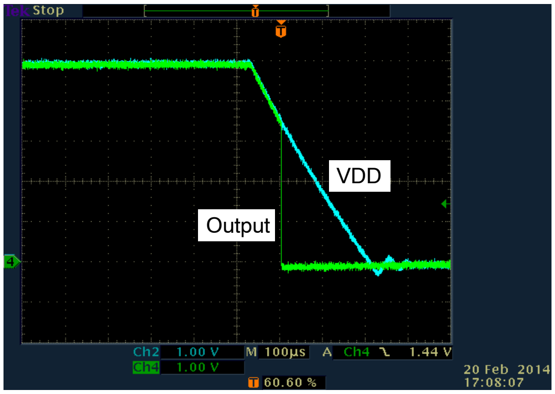


Figure 27. Output Behavior vs. Supply Voltage NCP81071B (Non−Inverting) 10 nF between Output and GND, INA = VDD, ENA = VDD

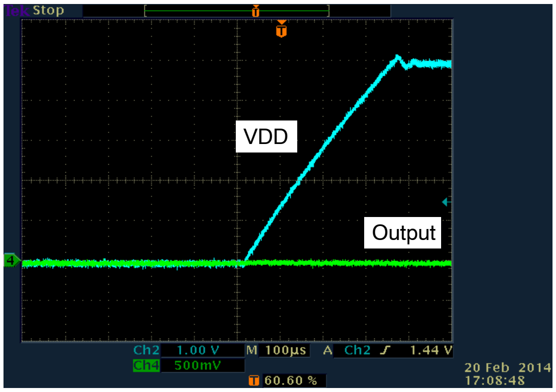


Figure 28. Output Behavior vs. Supply Voltage NCP81071B (Non−Inverting) 10 nF between Output and GND, INA = GND, ENA = VDD

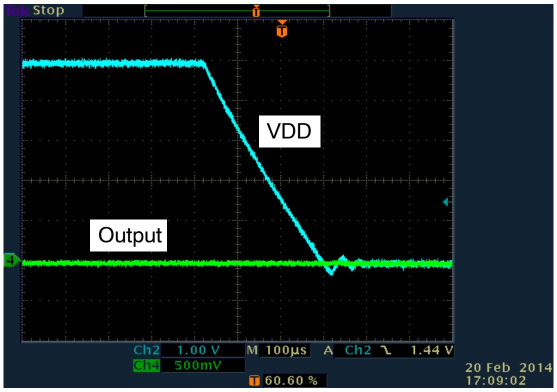


Figure 29. Output Behavior vs. Supply Voltage NCP81071B (Non−Inverting) 10 nF between Output and GND, INA = GND, ENA = VDD

LAYOUT GUIDELINES

The switching performance of NCP81071 highly depends on the design of PCB board. The following layout design guidelines are recommended when designing boards using these high speed drivers.

Place the driver as close as possible to the driven MOSFET.

Place the bypass capacitor between VDD and GND as close as possible to the driver to improve the noise filtering. It is preferred to use low inductance components such as chip capacitor and chip resistor. If vias are used, connect several paralleled vias to reduce the inductance of the vias.

Minimize the turn-on/sourcing current and turn-off/sinking current paths in order to minimize stray inductance. Otherwise high di/dt established in these loops with stray inductance can induce significant voltage spikes on the output of the driver and MOSFET Gate terminal.

Keep power loops as short as possible by paralleling the source and return traces (flux cancellation).

Keep low level signal lines away from high level power lines with a lot of switching noise.

Place a ground plane for better noise shielding. Beside noise shielding, ground plane is also useful for heat dissipation.

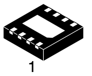
NCP81071 DFN and MSOP package have thermal pad for: 1) quiet GND for all the driver circuits; 2) heat sink for the driver. This pad must be connected to a ground plane and no switching currents from the driven MOSFET should pass through the ground plane under the driver. To maximize the heatsinking capability, it is recommended several ground layers are added to connect to the ground plane and thermal pad. A via array within the area of package can conduct the heat from the package to the ground layers and the whole PCB board. The number of vias and the size of ground plane are determined by the power dissipation of NCP81071 (VDD voltage, switching frequency and load condition), the air flow condition and its maximum junction temperature.

ORDERING INFORMATION

Part Number	Output Configuration	Temperature Range (°C)	Package Type	Shipping†
NCP81071ADR2G	dual inverting	−40 to +140	SOIC−8 (Pb−Free)	2500 / Tape & Reel
NCP81071BDR2G	dual non inverting			
NCP81071CDR2G	One inverting one non inverting			
NCP81071AZR2G	dual inverting		MSOP8 EP (Pb−Free)	3000 / Tape & Reel
NCP81071BZR2G	dual non inverting			
NCP81071CZR2G	One inverting one non inverting			
NCP81071AMNTXG	dual inverting		WDFN8 (Pb−Free)	3000 / Tape & Reel
NCP81071BMNTXG	dual non inverting			
NCP81071CMNTXG	One inverting one non inverting			

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

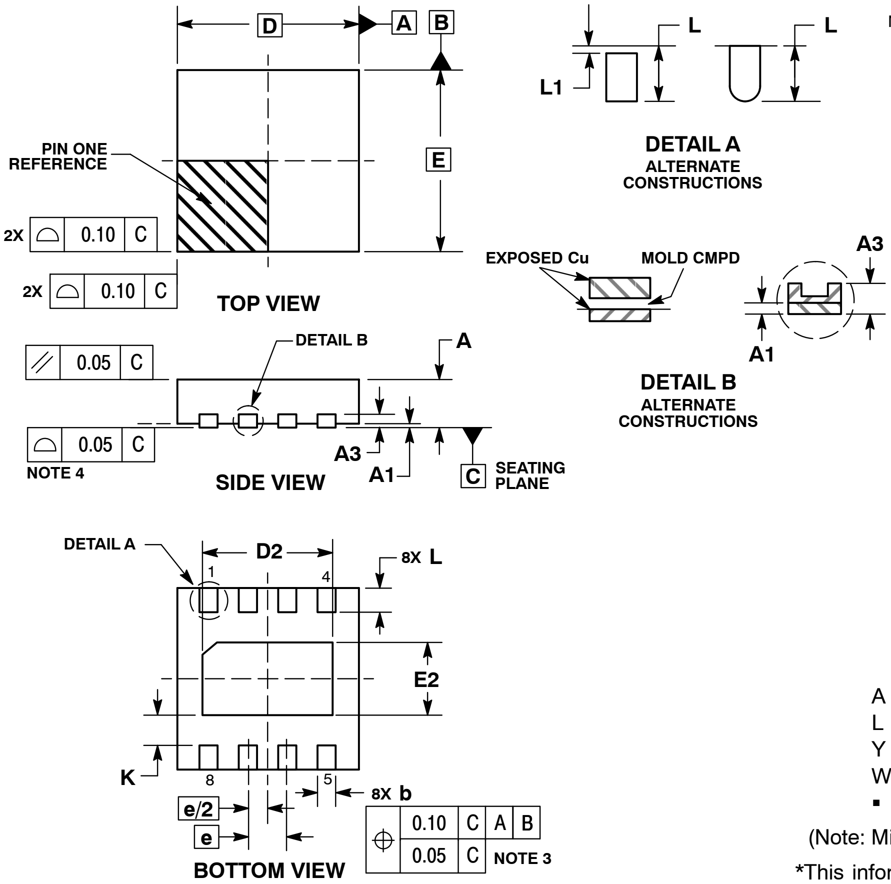
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS



SCALE 2:1

WDFN8 3x3, 0.65P
CASE 511CD
ISSUE O

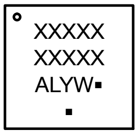
DATE 29 APR 2014



NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 MM FROM TERMINAL TIP.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

	MILLIMETERS	
DIM	MIN	MAX
A	0.70	0.80
A1	0.00	0.05
A3	0.20 REF	
b	0.25	0.35
D	3.00 BSC	
D2	2.05	2.25
E	3.00 BSC	
E2	1.10	1.30
e	0.65 BSC	
K	0.20	---
L	0.30	0.50
L1	0.00	0.15

GENERIC MARKING DIAGRAM*

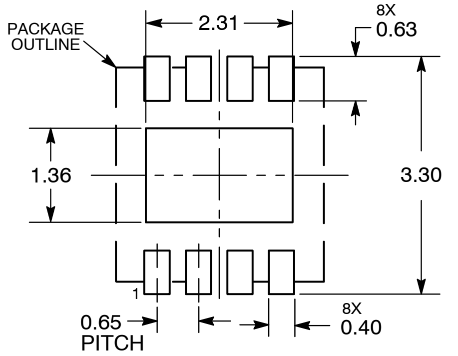


A = Assembly Location
L = Wafer Lot
Y = Year
W = Work Week
▪ = Pb−Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “ ▪”, may or may not be present.

RECOMMENDED SOLDERING FOOTPRINT*

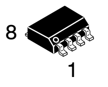


DIMENSIONS: MILLIMETERS

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

DOCUMENT NUMBER:	**98AON84944F**	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped “CONTROLLED COPY” in red.
DESCRIPTION:	**WDFN8, 3X3, 0.65P**	**PAGE 1 OF 1**

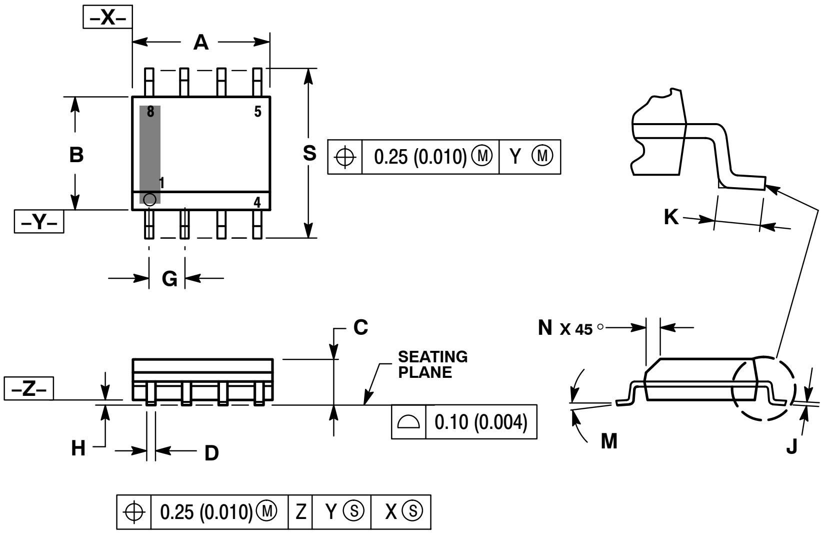
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS



SCALE 1:1

SOIC−8 NB
CASE 751−07
ISSUE AK

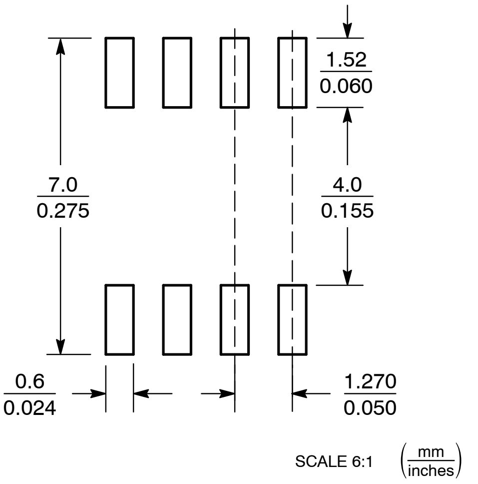
DATE 16 FEB 2011



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. 751−01 THRU 751−06 ARE OBSOLETE. NEW STANDARD IS 751−07.

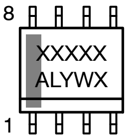
	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	4.80	5.00	0.189	0.197
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.053	0.069
D	0.33	0.51	0.013	0.020
G	1.27 BSC		0.050 BSC	
H	0.10	0.25	0.004	0.010
J	0.19	0.25	0.007	0.010
K	0.40	1.27	0.016	0.050
M	0 °	8 °	0 °	8 °
N	0.25	0.50	0.010	0.020
S	5.80	6.20	0.228	0.244

SOLDERING FOOTPRINT*

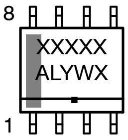


*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

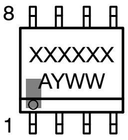
GENERIC MARKING DIAGRAM*



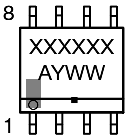
IC



IC (Pb−Free)



Discrete



Discrete (Pb−Free)

XXXXX = Specific Device Code
A = Assembly Location
L = Wafer Lot
Y = Year
W = Work Week
▪ = Pb−Free Package

XXXXXX = Specific Device Code
A = Assembly Location
Y = Year
WW = Work Week
▪ = Pb−Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “▪”, may or may not be present. Some products may not follow the Generic Marking.

STYLES ON PAGE 2

SOIC−8 NB
CASE 751−07
ISSUE AK

DATE 16 FEB 2011

STYLE 1:
PIN 1. EMITTER
2. COLLECTOR
3. COLLECTOR
4. EMITTER
5. EMITTER
6. BASE
7. BASE
8. EMITTER

STYLE 2:
PIN 1. COLLECTOR, DIE, #1
2. COLLECTOR, #1
3. COLLECTOR, #2
4. COLLECTOR, #2
5. BASE, #2
6. EMITTER, #2
7. BASE, #1
8. EMITTER, #1

STYLE 3:
PIN 1. DRAIN, DIE #1
2. DRAIN, #1
3. DRAIN, #2
4. DRAIN, #2
5. GATE, #2
6. SOURCE, #2
7. GATE, #1
8. SOURCE, #1

STYLE 4:
PIN 1. ANODE
2. ANODE
3. ANODE
4. ANODE
5. ANODE
6. ANODE
7. ANODE
8. COMMON CATHODE

STYLE 5:
PIN 1. DRAIN
2. DRAIN
3. DRAIN
4. DRAIN
5. GATE
6. GATE
7. SOURCE
8. SOURCE

STYLE 6:
PIN 1. SOURCE
2. DRAIN
3. DRAIN
4. SOURCE
5. SOURCE
6. GATE
7. GATE
8. SOURCE

STYLE 7:
PIN 1. INPUT
2. EXTERNAL BYPASS
3. THIRD STAGE SOURCE
4. GROUND
5. DRAIN
6. GATE 3
7. SECOND STAGE Vd
8. FIRST STAGE Vd

STYLE 8:
PIN 1. COLLECTOR, DIE #1
2. BASE, #1
3. BASE, #2
4. COLLECTOR, #2
5. COLLECTOR, #2
6. EMITTER, #2
7. EMITTER, #1
8. COLLECTOR, #1

STYLE 9:
PIN 1. EMITTER, COMMON
2. COLLECTOR, DIE #1
3. COLLECTOR, DIE #2
4. EMITTER, COMMON
5. EMITTER, COMMON
6. BASE, DIE #2
7. BASE, DIE #1
8. EMITTER, COMMON

STYLE 10:
PIN 1. GROUND
2. BIAS 1
3. OUTPUT
4. GROUND
5. GROUND
6. BIAS 2
7. INPUT
8. GROUND

STYLE 11:
PIN 1. SOURCE 1
2. GATE 1
3. SOURCE 2
4. GATE 2
5. DRAIN 2
6. DRAIN 2
7. DRAIN 1
8. DRAIN 1

STYLE 12:
PIN 1. SOURCE
2. SOURCE
3. SOURCE
4. GATE
5. DRAIN
6. DRAIN
7. DRAIN
8. DRAIN

STYLE 13:
PIN 1. N.C.
2. SOURCE
3. SOURCE
4. GATE
5. DRAIN
6. DRAIN
7. DRAIN
8. DRAIN

STYLE 14:
PIN 1. N−SOURCE
2. N−GATE
3. P−SOURCE
4. P−GATE
5. P−DRAIN
6. P−DRAIN
7. N−DRAIN
8. N−DRAIN

STYLE 15:
PIN 1. ANODE 1
2. ANODE 1
3. ANODE 1
4. ANODE 1
5. CATHODE, COMMON
6. CATHODE, COMMON
7. CATHODE, COMMON
8. CATHODE, COMMON

STYLE 16:
PIN 1. EMITTER, DIE #1
2. BASE, DIE #1
3. EMITTER, DIE #2
4. BASE, DIE #2
5. COLLECTOR, DIE #2
6. COLLECTOR, DIE #2
7. COLLECTOR, DIE #1
8. COLLECTOR, DIE #1

STYLE 17:
PIN 1. VCC
2. V2OUT
3. V1OUT
4. TXE
5. RXE
6. VEE
7. GND
8. ACC

STYLE 18:
PIN 1. ANODE
2. ANODE
3. SOURCE
4. GATE
5. DRAIN
6. DRAIN
7. CATHODE
8. CATHODE

STYLE 19:
PIN 1. SOURCE 1
2. GATE 1
3. SOURCE 2
4. GATE 2
5. DRAIN 2
6. MIRROR 2
7. DRAIN 1
8. MIRROR 1

STYLE 20:
PIN 1. SOURCE (N)
2. GATE (N)
3. SOURCE (P)
4. GATE (P)
5. DRAIN
6. DRAIN
7. DRAIN
8. DRAIN

STYLE 21:
PIN 1. CATHODE 1
2. CATHODE 2
3. CATHODE 3
4. CATHODE 4
5. CATHODE 5
6. COMMON ANODE
7. COMMON ANODE
8. CATHODE 6

STYLE 22:
PIN 1. I/O LINE 1
2. COMMON CATHODE/VCC
3. COMMON CATHODE/VCC
4. I/O LINE 3
5. COMMON ANODE/GND
6. I/O LINE 4
7. I/O LINE 5
8. COMMON ANODE/GND

STYLE 23:
PIN 1. LINE 1 IN
2. COMMON ANODE/GND
3. COMMON ANODE/GND
4. LINE 2 IN
5. LINE 2 OUT
6. COMMON ANODE/GND
7. COMMON ANODE/GND
8. LINE 1 OUT

STYLE 24:
PIN 1. BASE
2. EMITTER
3. COLLECTOR/ANODE
4. COLLECTOR/ANODE
5. CATHODE
6. CATHODE
7. COLLECTOR/ANODE
8. COLLECTOR/ANODE

STYLE 25:
PIN 1. VIN
2. N/C
3. REXT
4. GND
5. IOUT
6. IOUT
7. IOUT
8. IOUT

STYLE 26:
PIN 1. GND
2. dv/dt
3. ENABLE
4. ILIMIT
5. SOURCE
6. SOURCE
7. SOURCE
8. VCC

STYLE 27:
PIN 1. ILIMIT
2. OVLO
3. UVLO
4. INPUT+
5. SOURCE
6. SOURCE
7. SOURCE
8. DRAIN

STYLE 28:
PIN 1. SW_TO_GND
2. DASIC_OFF
3. DASIC_SW_DET
4. GND
5. V_MON
6. VBULK
7. VBULK
8. VIN

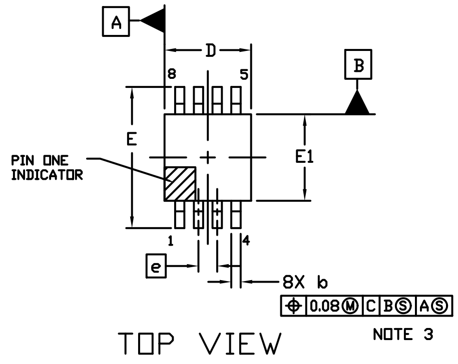
STYLE 29:
PIN 1. BASE, DIE #1
2. EMITTER, #1
3. BASE, #2
4. EMITTER, #2
5. COLLECTOR, #2
6. COLLECTOR, #2
7. COLLECTOR, #1
8. COLLECTOR, #1

STYLE 30:
PIN 1. DRAIN 1
2. DRAIN 1
3. GATE 2
4. SOURCE 2
5. SOURCE 1/DRAIN 2
6. SOURCE 1/DRAIN 2
7. SOURCE 1/DRAIN 2
8. GATE 1

SCALE 1:1

MSOP8 EP, 3x3
CASE 846AM
ISSUE A

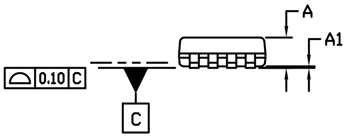
DATE 05 OCT 2021



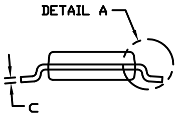
TOP VIEW

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.10 mm IN EXCESS OF MAXIMUM MATERIAL CONDITION.
4. DIMENSION D DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.15 mm PER SIDE. DIMENSION E DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 mm PER SIDE. DIMENSIONS D AND E ARE DETERMINED AT DATUM F.
5. DATUMS A AND B ARE TO BE DETERMINED AT DATUM F.
6. A1 IS DEFINED AS THE VERTICAL DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.

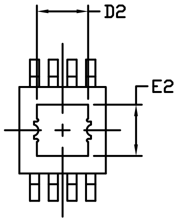


SIDE VIEW

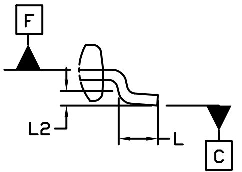


END VIEW

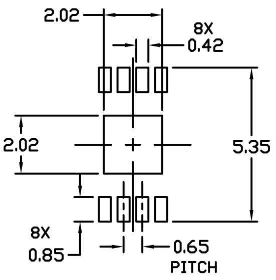
	MILLIMETERS	
DIM	MIN.	MAX.
A	---	1.10
A1	0.05	0.15
b	0.25	0.40
c	0.13	0.23
D	2.90	3.10
D2	1.73	1.83
E	4.75	5.05
E1	2.90	3.10
E2	1.37	1.47
e	0.65 BSC	
L	0.40	0.70
L2	0.254 BSC	



BOTTOM VIEW

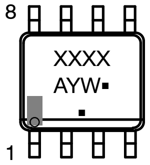


DETAIL A



RECOMMENDED
MOUNTING FOOTPRINT

GENERIC MARKING DIAGRAM*



XXXX = Specific Device Code
A = Assembly Location
Y = Year
W = Work Week
▪ = Pb−Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “▪”, may or may not be present. Some products may not follow the Generic Marking.

DOCUMENT NUMBER:	**98AON82708F**	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped “CONTROLLED COPY” in red.
DESCRIPTION:	**MSOP8 EP, 3X3**	**PAGE 1 OF 1**